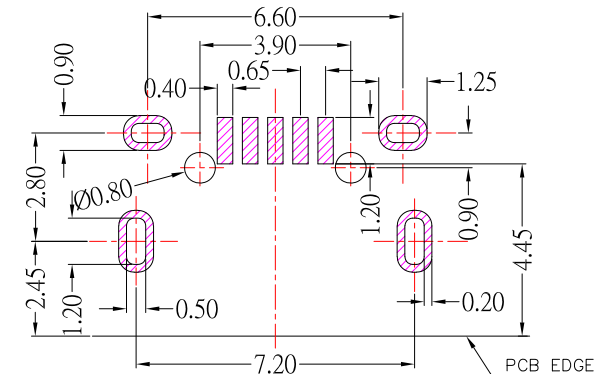


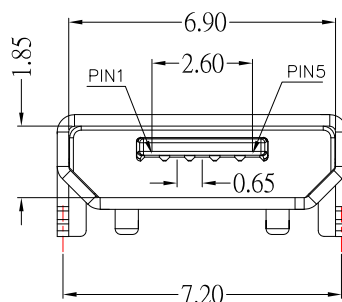
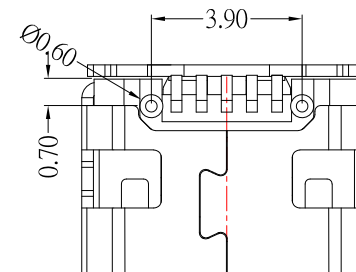
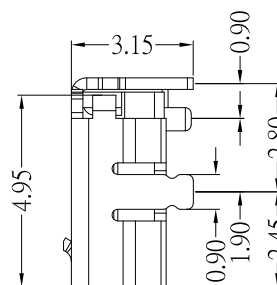
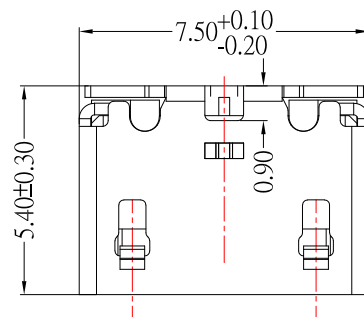
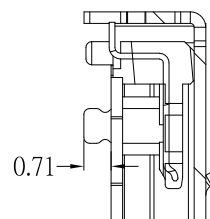
MRUSB-5BED14Bx-S347

SHELL 鍍層:

TN
NI



P.C.B LAYOUT



NOTES:

1.MATERIAL:

- 1.1 HOUSING: LCP
- 1.2 CONTACT: PHOSPHOR BRONZE
- 1.3 SHELL: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Tin or Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.8 A (PIN1,5) ; 1.0 A (PIN2,3,4)
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ± 0.2
Above 5 ~ 15 ± 0.3
Above 15 ~ 30 ± 0.4
Above 30 ~ 50 ± 0.5
Angle ± 0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:

Jack Lu

DATE

12/26/25

MAT'L

FINISH

SCALE

SHEET NO.

TITLE

MODLE

DWG NO.

PART NO.

CONNECTOR

MICRO USB 5BF 牛角(PH7.2-6.6) 有柱,無捲邊

MRUSB5B-ED14Bx-S347

1 of 1

SIZE

A4

VER

R2

ITEM NO.

DESCRIPTION

DRAWN DATE

Jack 122625

Jack 082923

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